

FIG. 1 (RELATED ART)



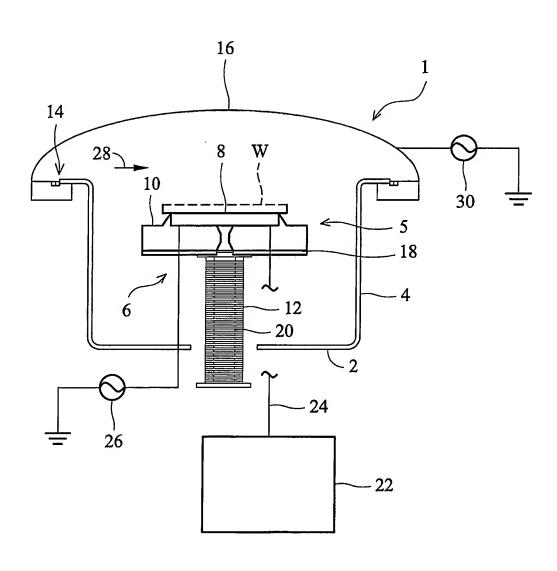


FIG. 2

Replacement Sheet 0503-A30494-USf1/dwwang/touko JUN 2 7 2005 ETCH TRENCH OPENINGS AND _ 1a VIA OPENINGS IN DIELECTRIC LAYERS ON WAFER PLACE WAFER IN PRE-CLEANING 2a **CHAMBER** SUBJECT WAFER TO 3a PRE-CLEANING/DE-CASSING REMOVE WAFER FROM _ 4a PRE-CLEANING CHAMBER DAPOSIT BARRIER LAYER IN __ 5a TRENCH OPENINGS AND VIA **OPENINGS** DAPOSIT SEED LAYER ON BARRIER _ 6a LAYER FILL TRENCH OPENINGS AND VIA _ 7a OPENINGS USING ECP

FIG. 3